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(54) Title: CIRCUIT BOARD HAVING AN ELECTRODEPOSITED COATING ON A CONDUCTIVE CORE WITHIN A VIA AND METHOD OF MAKING SAME

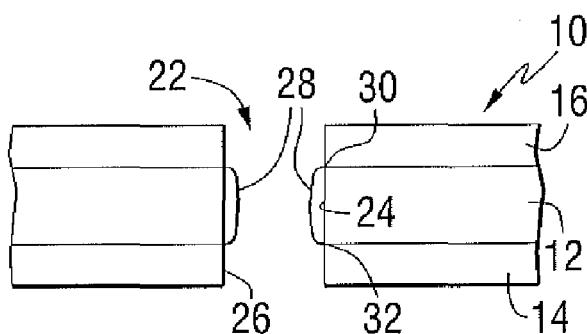


FIG. 6

(57) Abstract: A process for fabricating a circuit board includes: providing a substrate (10) including a first electrically conductive core (12) having a first insulating coating (14) on a first side and a second insulating coating (16) on a second side, forming an opening (22) in the first and second insulating coatings and the first electrically conductive core, exposing an edge (24) of the conductive core within the opening, and electrodepositing a third insulating material (28) on the exposed edge of the first electrically conductive core. A circuit board fabricated using the process is also provided.



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